

IN THE CLAIMS

Claims 1-13 have been previously canceled without prejudice.

Please amend claims 14 and 16.

Please add new claims 18 - 23.

Please enter the pending claims as follows:

1. – 13. (Canceled)

14. (Currently Amended) A self-aligned mechanical joint exposed to microwave energy comprising:

a bump on a die ~~, said bump comprising electroplated copper;~~

and

a solder on a substrate wherein said solder reflows ~~was~~ ~~reflowed~~ by indirect heat through conduction from said bump upon absorption of said microwave energy by said die.

15. (Original) The mechanical joint of claim 14 wherein said microwave energy has variable frequency.

16. (Currently Amended) The mechanical joint of claim 14 wherein said bump reflows ~~was reflowed~~ by microwave energy.

17. (Original) The mechanical joint of claim 16 wherein said microwave energy has variable frequency.

18. (New) The mechanical joint of claim 14 wherein said bump comprises copper.

19. (New) The mechanical joint of claim 14 wherein said bump is electroplated.

20. (New) The mechanical joint of claim 14 wherein said bump has a columnar shape.

21. (New) The mechanical joint of claim 14 wherein said solder comprises a eutectic solder of lead and tin.

22. (New) The mechanical joint of claim 14 wherein said solder comprises a binary alloy of tin and silver.

23. (New) The mechanical joint of claim 14 wherein said solder comprises a ternary alloy of tin, copper, and silver.